2SC2229

Rev.E Mar.-2016

DATA SHEET

/ Descriptions

WR0<50P ṂṂÞ QSQ ÆṀч s ‖ ㄱ Silicon NPN transistor in a TO-92LM Plastic Package.

/ Features

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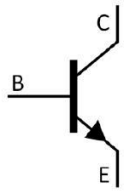
High breakdown voltage, low output capacitance, high f_T.

/ Applications

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TV video output, high voltage switching and driver stage of audio amplifier applications.

/ Equivalent Circuit



/ Pinning



PIN1 χ Base PIN 2 χ Collector PIN 3 χ Emitter

/ h_{FE} Classifications & Marking

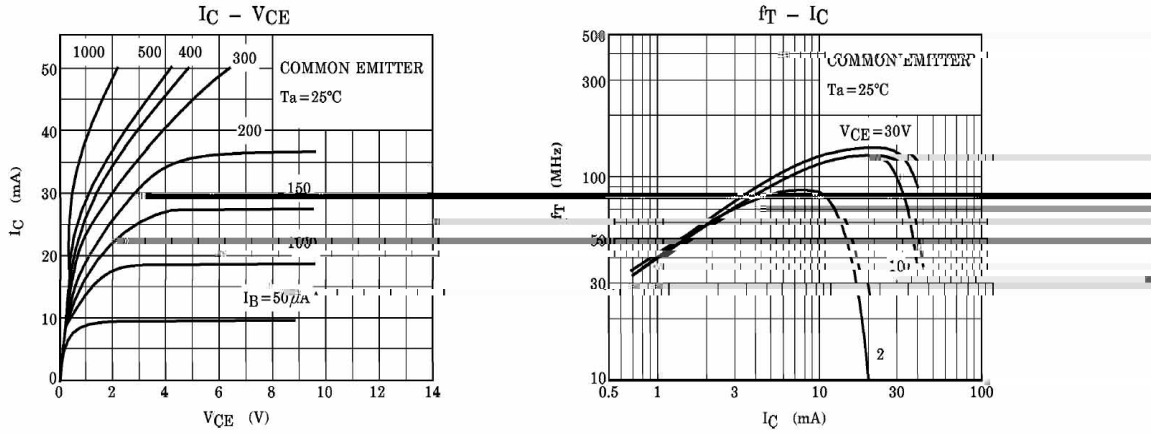
h_{FE} Classifications Symbol	O	Y
h_{FE} Range	70 140	120 240

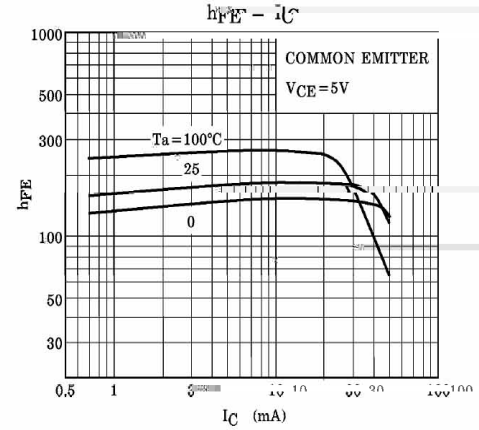
bol	Ѝ Ѯ Ё Rating	D Ц Unit
o	200	V
o	150	V
o	5.0	V
	50	mA
	-55	mA
	800	mW
	150	
	-55 150	

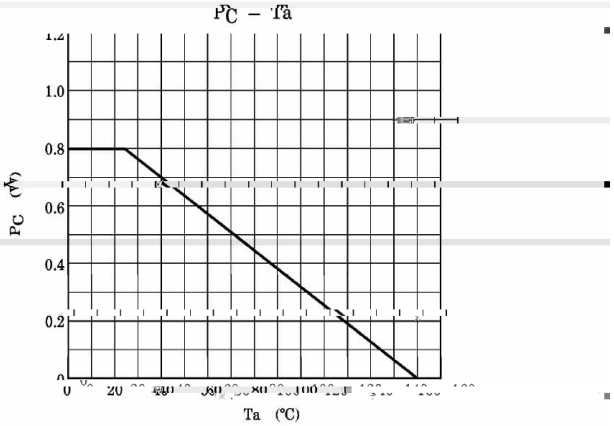
ns	ѱ ѝ Ё Min	Ɛ ѯ Ё Typ	ѱ ѕ Ё Max	D Ц Unit
)			0.1	μA
)			0.1	μA

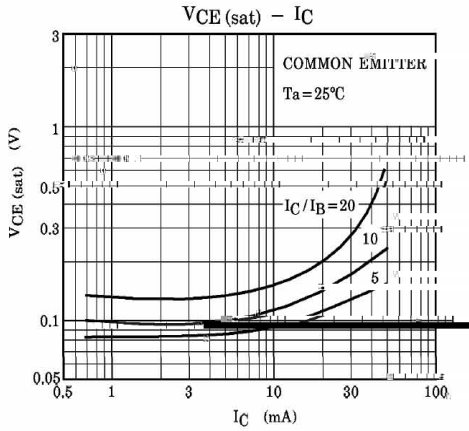
DC Current Gain h_{FE}

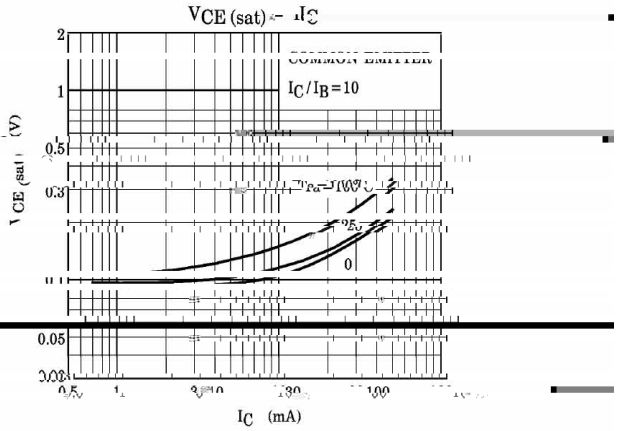
/ Electrical Characteristic Curve





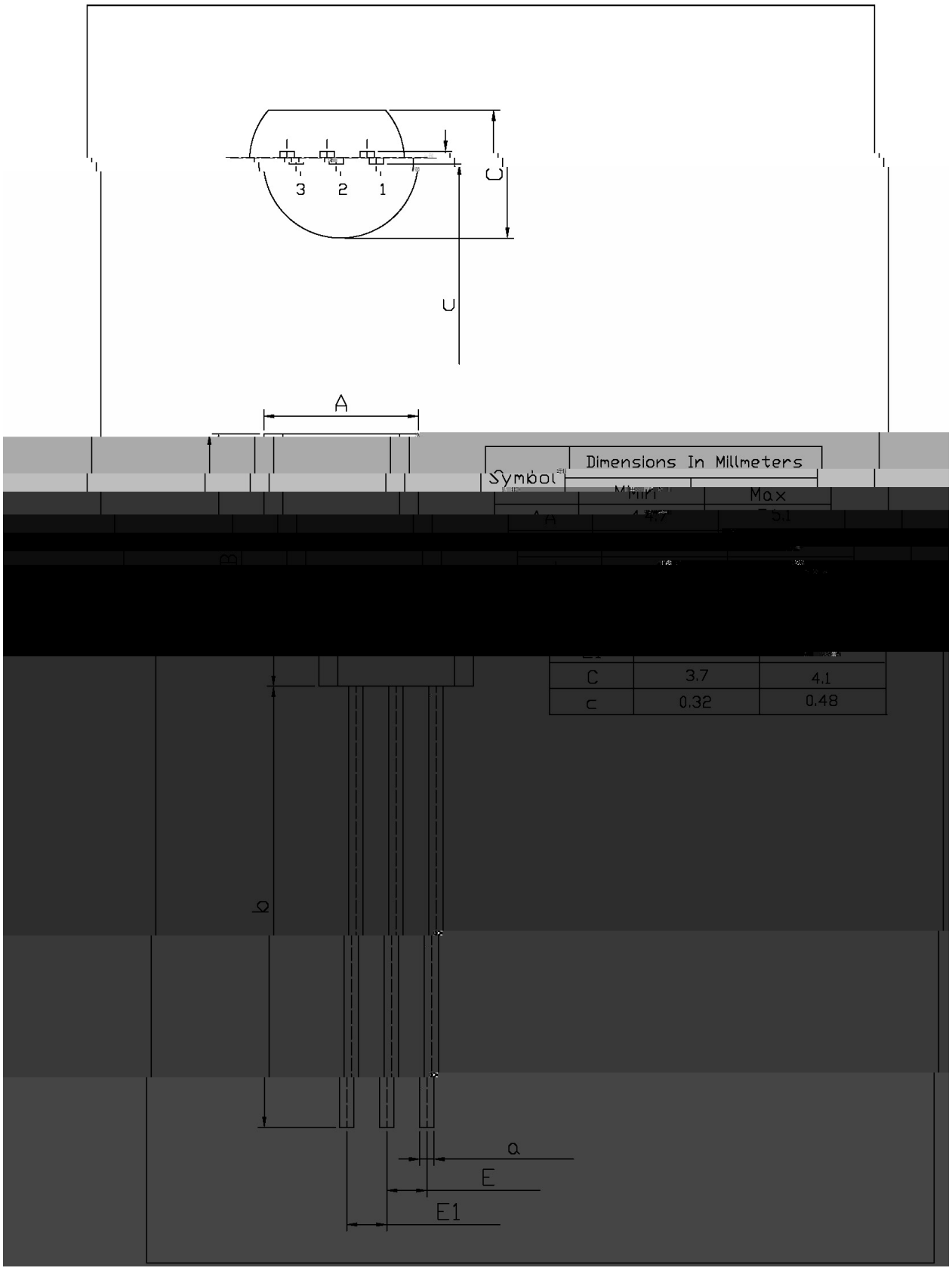






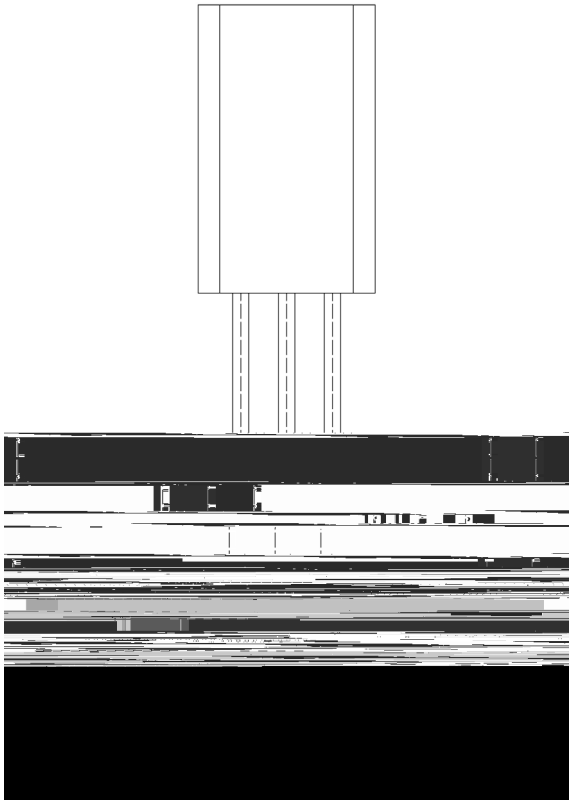
/ Package Dimensions

TO-92LM Unit: mm



Symbol	Dimensions In Millmeters	
	Min	Max
C	3.7	4.1
c	0.32	0.48

/ Marking Instructions

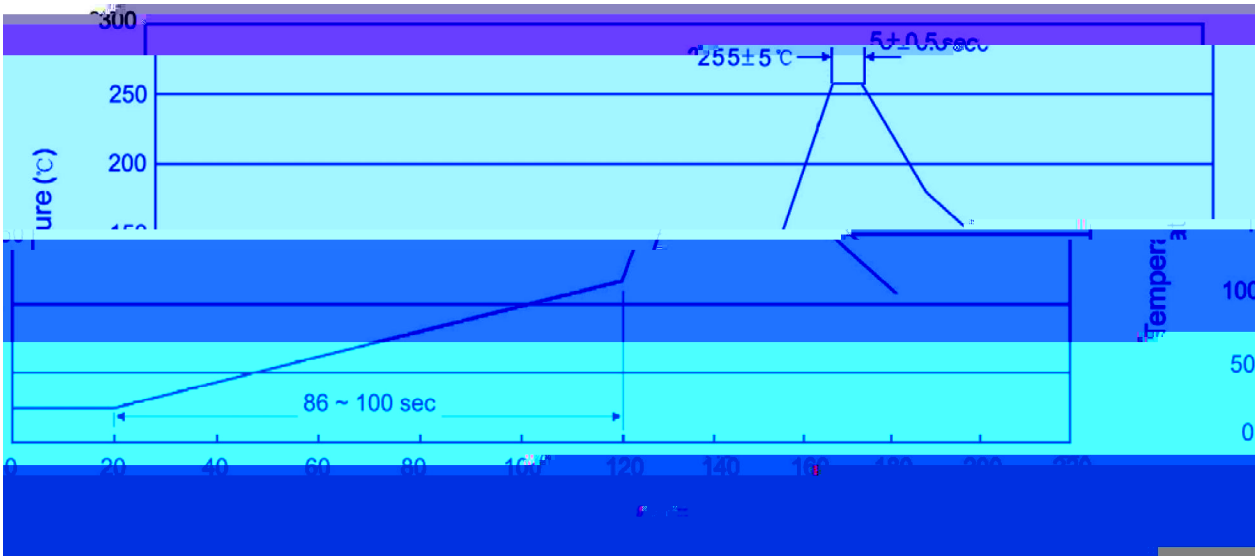


ᄂ ˝ χ

EU=

F555< χ

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 255 ° 5 ł ı ˋH ڑ ˋY ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ɔ ﻉ ỷ ㎛ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ł	ˋH ڑ χ 10 ° 1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

ˇQ ţ ｙ Ł / BULK